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**Zeon to Start Production of High Thermal Interface Materials(TIM)**  
 ~ Contributing Solutions to Thermal Problems in Electronic Components  
 Through High Thermal Conductivity and Durability ~

Zeon Corporation

Zeon Corporation (president: Kimiaki Tanaka) will start the production of sheet-based thermal interface materials, the “VB Series”, developed by Zeon’s original manufacturing technology. Compared to grease, which is the generally used heat dissipation material, Zeon’s product demonstrates superiority in terms of thermal conductivity, durability, and workability. Therefore, It is expected to greatly contribute to solving thermal problems in electronic components and devices.

In recent years, with the improvement of information processing capability of chips for servers and communication equipment, the demand for heat countermeasures has increased.

Zeon’s “VB200”, which has just started production, is the standard grade of the VB series. Compared to other broadly used thermal interface materials, it offers high thermal conductivity in the vertical direction (Z Axis, or thickness direction), while simultaneously exhibiting excellent durability by applying the special elastomer technology in which Zeon excels.

In the future of the semiconductor industry, the problem of heat generation is expected to become more and more pronounced as devices become smaller and faster. Zeon’s thermal interface material is expected not only to solve the problems associated with the high performance of these semiconductors, but also other electronics devices that require thermal management.

Characteristics	VB200
Thickness	80 $\mu$ m ~ 500 $\mu$ m
Thermal Conductivity (Z Axis)	38 W/m · k
Hardness*1	96
Compressibility*2	11%

\* 1 Measured with Asker Durometer type C

\* 2 Measured under conditions of 100 $\mu$ m thickness, 50°C temperature, and 0.3 MPa pressure

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